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Siliup Semiconductor

SP010N02GHTF

100V N-Channel Power MOSFET

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
100V	1.7mΩ@10V	300A

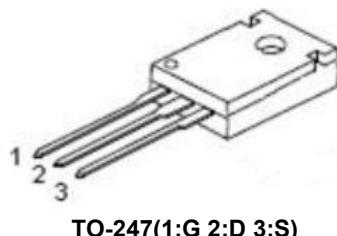
Feature

- Fast Switching
- Low Gate Charge and Rdson
- 100% Single Pulse avalanche energy Test

Applications

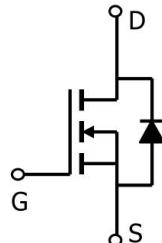
- Power switching application
- DC-DC Converter
- Power Management

Package

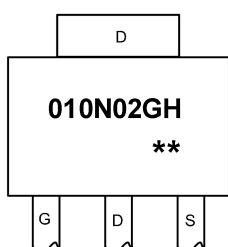


TO-247(1:G 2:D 3:S)

Circuit diagram



Marking



010N02GH : Product code
** : Week code



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Absolute maximum ratings (Ta=25°C,unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain source voltage	V _{DS}	100	V
Gate source voltage	V _{GS}	±20	V
Continuous drain current(Tc=25°C)	I _D	300	A
Pulsed drain current	I _{DM}	1200	A
Power dissipation(Tc=25°C)	P _D	360	W
Single pulsed avalanche energy1)	E _{AS}	550	mJ
Thermal resistance, junction-case	R _{θJC}	0.34	°C/W
Operation and storage temperature	T _{stg} , T _j	-55 to 150	°C

Electrical characteristics (Ta=25°C, unless otherwise noted)

Characteristics	Symbol	Test Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	I _D = 250μA, V _{GS} = 0V	100	-	-	V
Drain Cut-Off Current	I _{DSS}	V _{DS} = 80V, V _{GS} = 0V	-	-	1	μA
Gate Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V	-	-	±0.1	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	2.0	2.7	4.0	V
Drain-Source ON Resistance	R _{DS(ON)}	V _{GS} = 10V, I _D = 20A	-	1.7	2.2	mΩ
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} = 50V, V _{GS} = 0V, f = 1.0MHz	-	9625	-	pF
Output Capacitance	C _{oss}		-	1608	-	
Reverse Transfer Capacitance	C _{rss}		-	75	-	
Switching Characteristics						
Total Gate Charge	Q _g	V _{DS} =50V , V _{GS} =10V , ID=20A	-	160	-	nC
Gate-Source Charge	Q _{gs}		-	31	-	
Gate-Drain Charge	Q _{gd}		-	37	-	
Turn-On Delay Time	t _{d(on)}	V _{GS} = 10V, V _{DS} = 50V, RL=2.5Ω , R _G = 6.0Ω	-	35	-	ns
Rise Time	t _r		-	68	-	
Turn-Off Delay Time	t _{d(off)}		-	150	-	
Fall Time	t _f		-	105	-	
Drain-Source Body Diode Characteristics						
Source-Drain Diode Forward Voltage	V _{SD}	I _S = 1A, V _{GS} = 0V	-	-	1.2	V

Note:

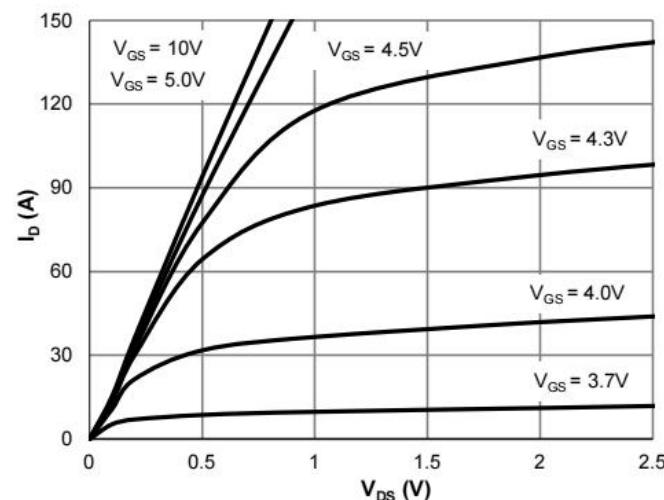
- E_{AS} is tested at starting T_j = 25°C, V_{DD}=50V,V_{GS} = 10V,L = 0.5mH, R_g=25mΩ;



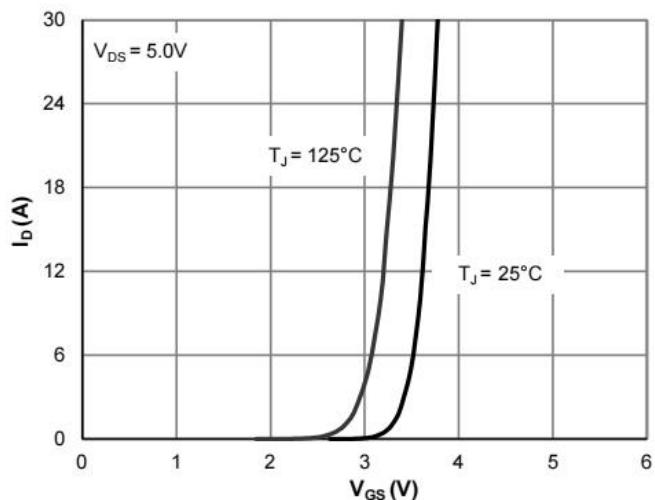
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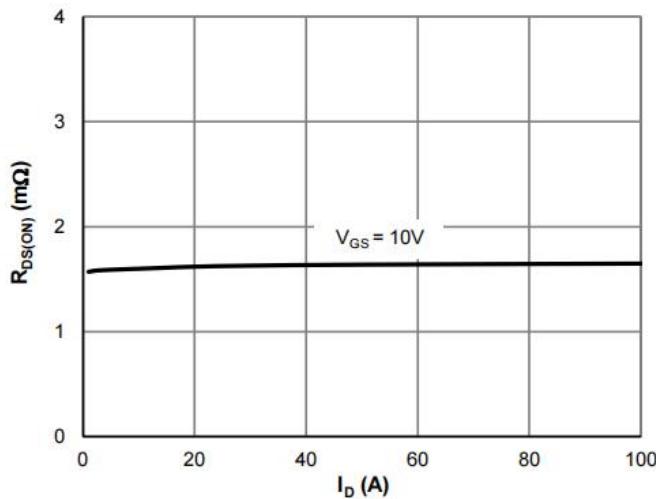
Typical Characteristics



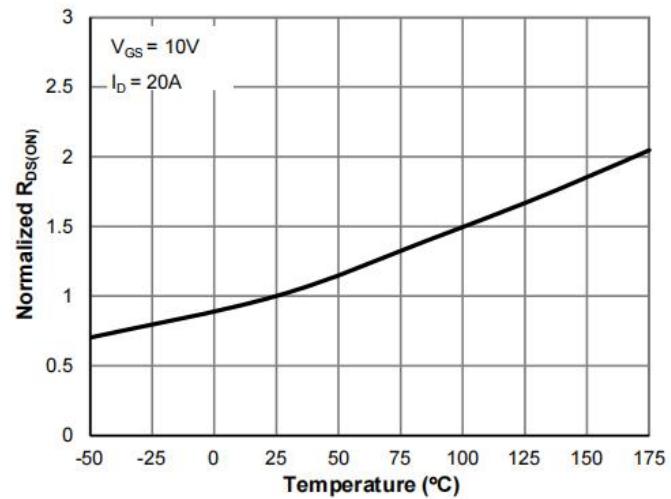
Typical Output Characteristics



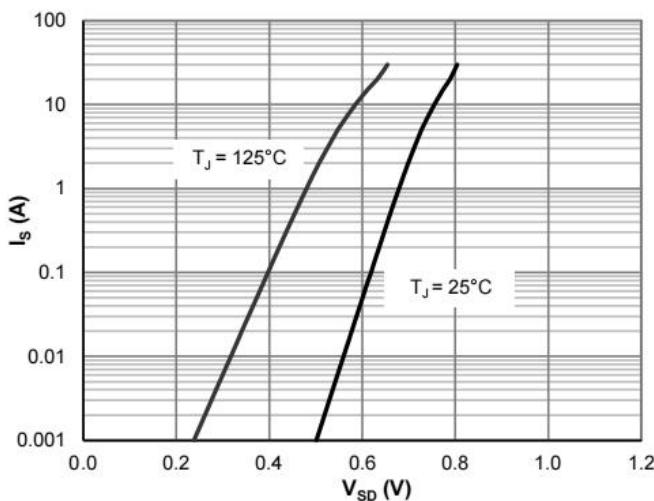
Transfer Characteristics



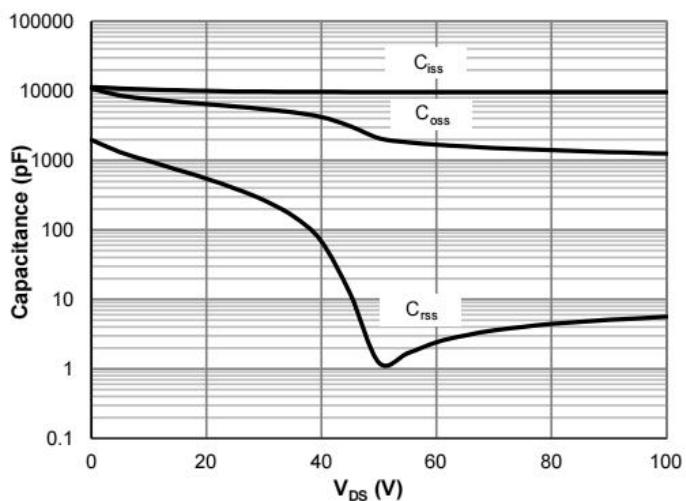
On-Resistance vs. Drain Current



On-Resistance vs. Junction Temperature



Body-Diode Characteristics



Capacitance Characteristics

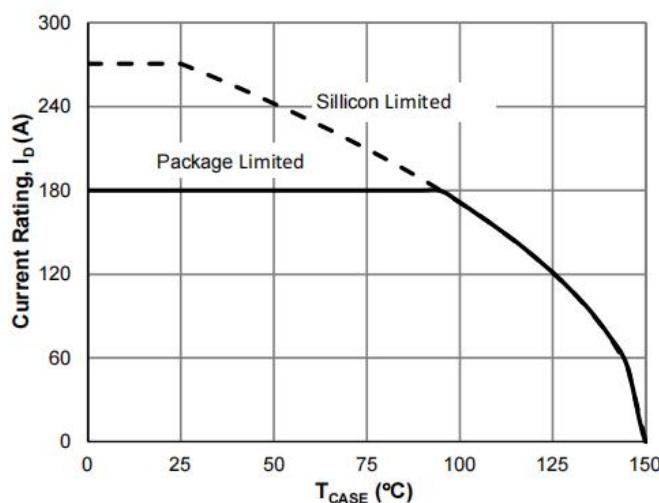


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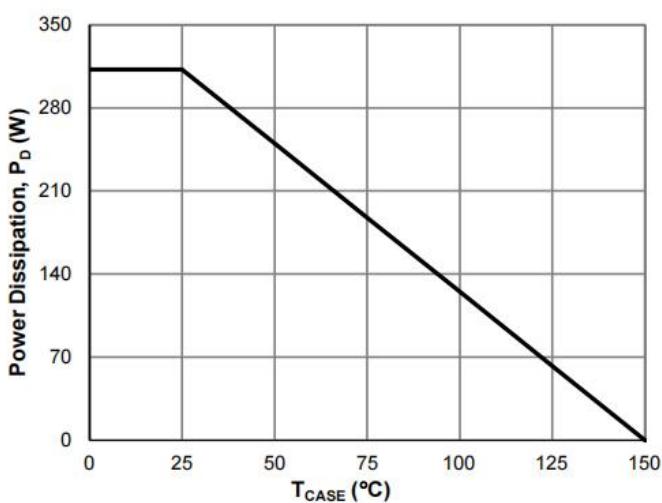
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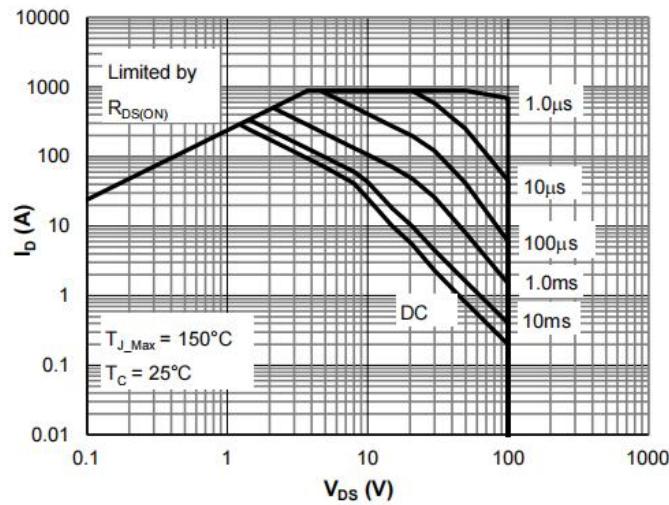
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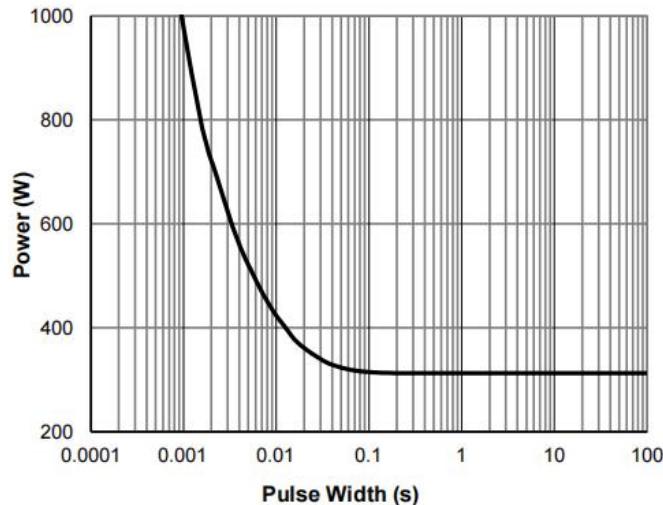
Current De-rating



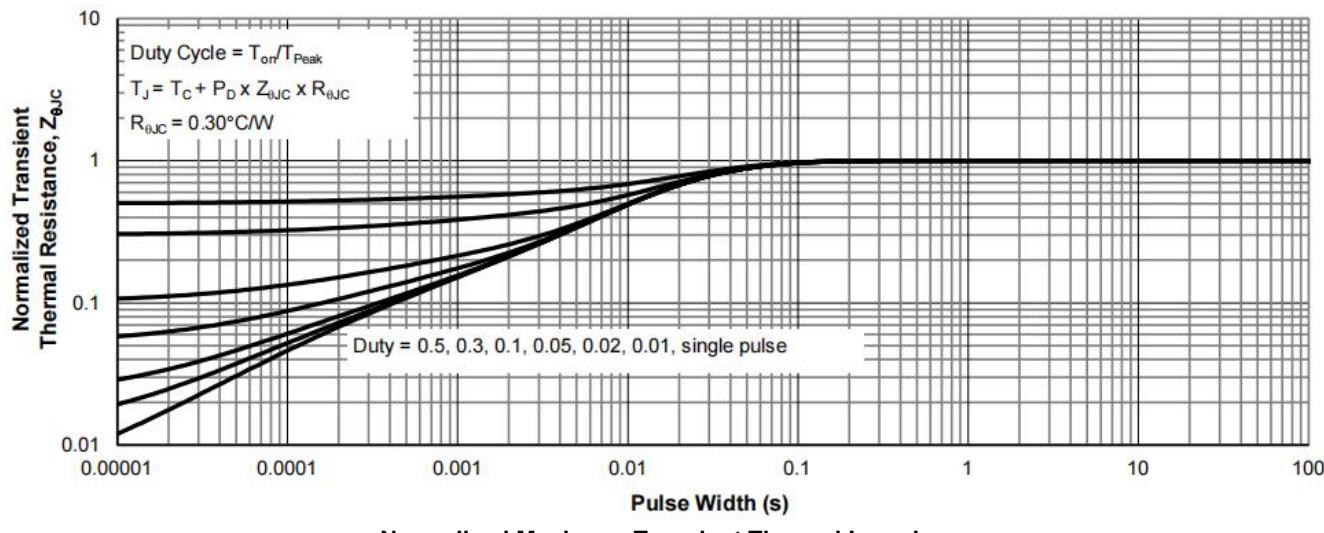
Power De-rating



Maximum Safe Operating Area



Single Pulse Power Rating, Junction-to-Case





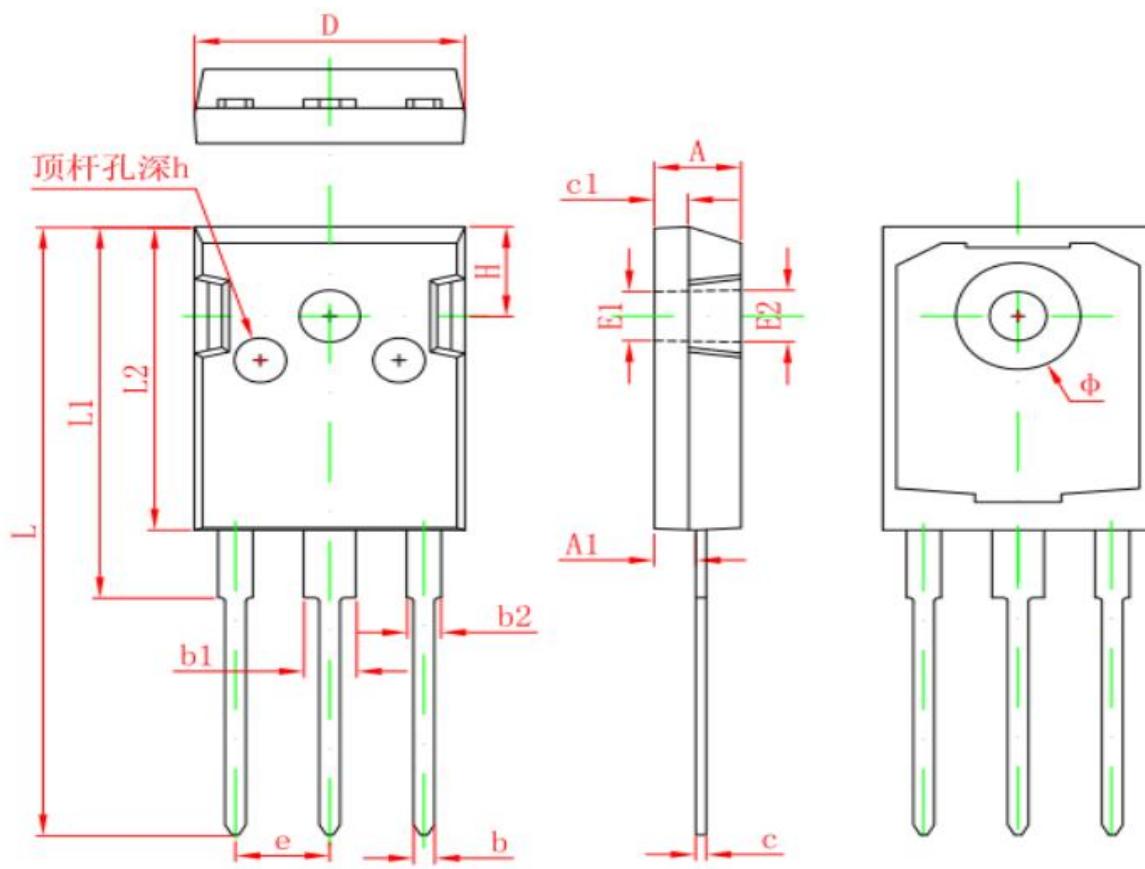
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TO-247 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.850	5.150	0.191	0.200
A1	2.200	2.600	0.087	0.102
b	1.000	1.400	0.039	0.055
b1	2.800	3.200	0.110	0.126
b2	1.800	2.200	0.071	0.087
c	0.500	0.700	0.020	0.028
c1	1.900	2.100	0.075	0.083
D	15.450	15.750	0.608	0.620
E1	3.500 REF.		0.138 REF.	
E2	3.600 REF.		0.142 REF.	
L	40.900	41.300	1.610	1.626
L1	24.800	25.100	0.976	0.988
L2	20.300	20.600	0.799	0.811
Φ	7.100	7.300	0.280	0.287
e	5.450 TYP.		0.215 TYP.	
H	5.980 REF.		0.235 REF.	
h	0.000	0.300	0.000	0.012